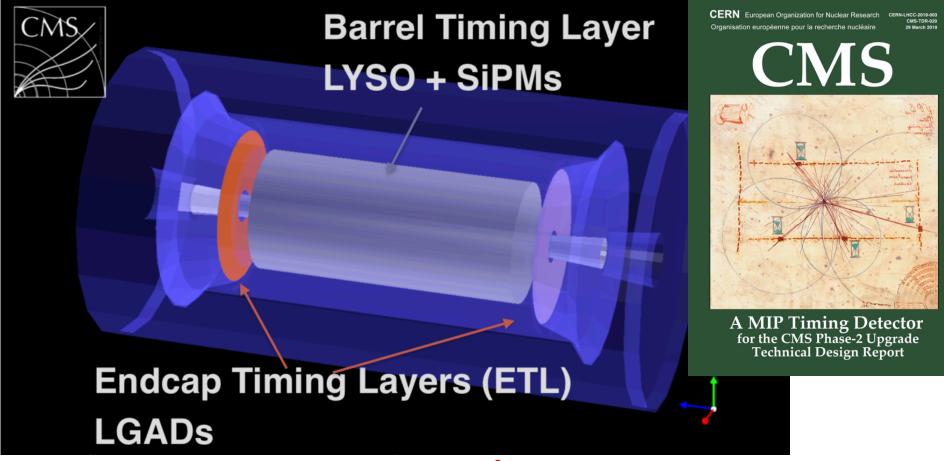
CMS Timing Detector (MTD) Electronics

Ted Liu, Fermilab

On behalf of the MTD collaboration



First generation precision timing detectors \rightarrow challenging front-end electronics

- Thin layers between tracker and calorimeters (BTL single layer, ETL double)
- with ~30-40 ps per track resolution at HL-LHC start, & < 60 ps at 3000 fb⁻¹

BTL precision timing *challenges*

LYSO with dual-end SiPM readout

- Basic unit: 1x16 array of crystals (~ 3 x 3 x 57 mm³)
- |η|<1.45, surface ~38 m²; 332k channels
- Nominal fluence: <u>1.9x10¹⁴ n_{eq}/cm²</u> (3000 fb⁻¹)
- Single layer

Huge MIP signal size

- Signal: 10k 6k photoelectrons; + SiPM gain: 4 1.5 10⁵
- Peaking time ~20 ns, LYSO decay time constant ~40 ns
- timing is given by the arrival of the first photoelectrons (20-100 p.e. depending on DCR) – 2 per mil of the signal matters

• Dark count rate (DCR) and out-of-time pileup

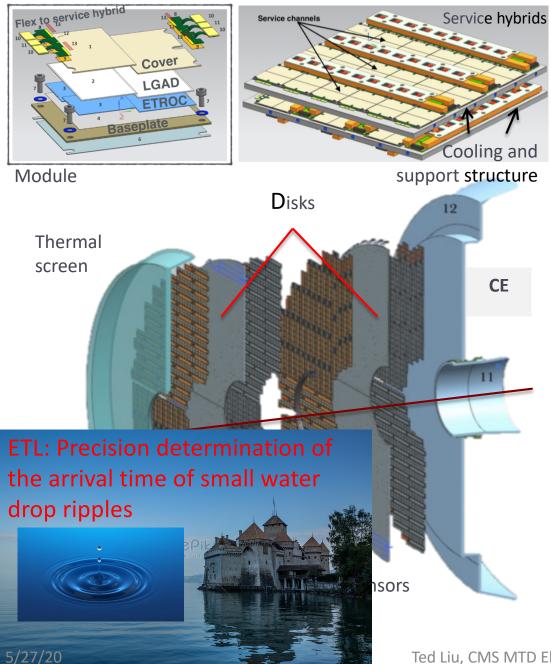
noise is dominated by SiPM dark counts, out-of-time pileup → baseline fluctuations. Due to radiation along BTL lifetime, SiPM DCR rate grows from 1 MHz to 55 GHz

The need for DCR cancellation at front-end



BTL: Precision determination of the arrival time of huge waves

ETL precision timing *challenges*



- Low Gain Avalanche Detectors (LGADs)
 - Basic unit: Module (4x6 cm²)
 - 2x4 cm² LGAD bump-bonded to 2 ETROC ASICs mounted on two sides of cooling plates
 - Two layers/disks per endcap mounted on the HGC nose (~2 hits per track)
 - 1.6 < |η| < 3.0, surface ~14 m²; ~8.5 M channels
 - Nominal fluence: 1.6x10¹⁵ n_{ea}/cm² (@ 3000 fb⁻¹)
 - LGAD gain modest: 10-30
 - Landau contribution: ~ 30-40ps
 - Front-end contribution kept < ~40ps
- Extract precision timing from small LGAD signal (~6fC) at end of operation With low power: < 4mW/channel

Challenges:

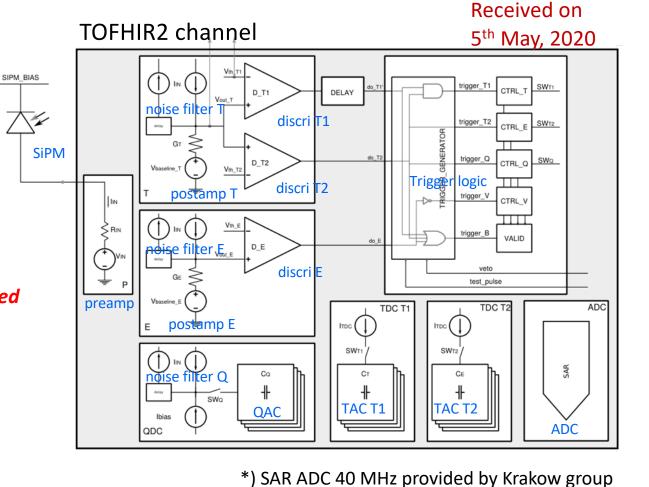
- minimize impact of DCR noise and pileup on time resolution
- cope with very high rate (2.5 MHz MIP + 5 MHz low E hits per channel) •
- handle the dynamic range variation along detector lifetime
- 15mW/channel •



Amplitude measurement Charge integration and ToT/Slew Rate Accuracy 2% for time walk correction

DCR cancellation noise and baseline fluctuation are mitigated by a dedicated pulse filtering circuit.

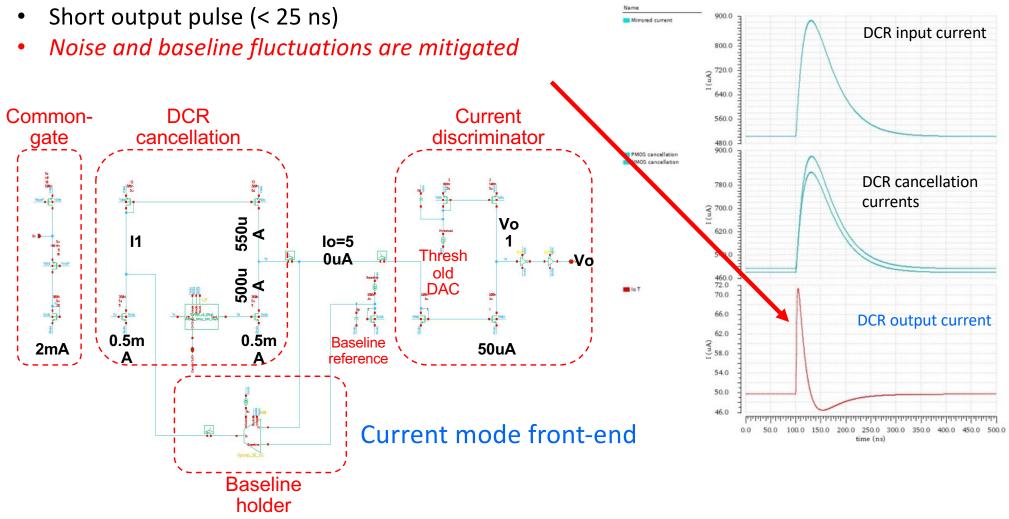




BTL TOFHIR: Time Of Flight at High Rate TOFHIR2 8.5 x 5.2 mm²

TOFHIR2 DCR cancellation

- Inverted and delayed pulse added to the original pulse
- Delay line is approximated by a RC net, programmable 0.2-0.5ns

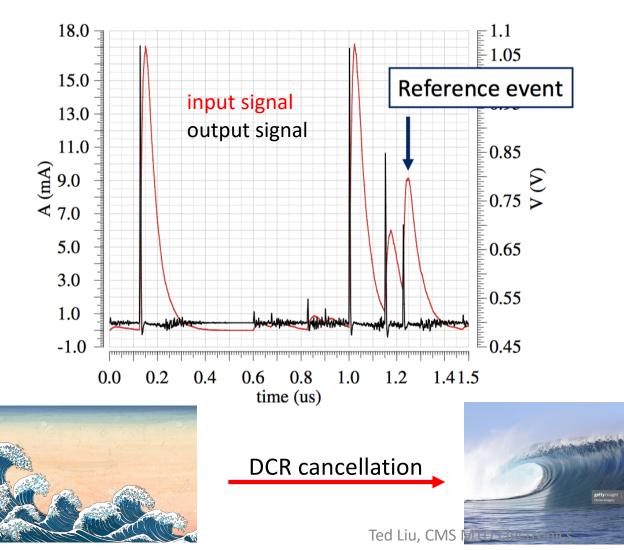


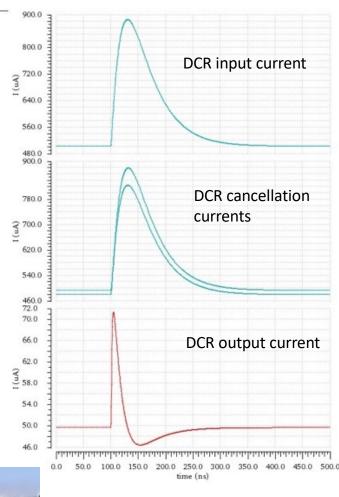
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The effect of DCR cancellation

Noise and baseline fluctuations are mitigated

• at the highest DCR the time resolution is improved by a factor 3.5





Sharper waves, well separated in time...

TOFHIR versions

- TOFHIR1 (UMC 110 nm): Available, *and enables system level testing*
- TOFHIR2 (TSMC 130 nm): Chips received in May 2020

TOFHIR2:

- New technology
- New frontend design
- DCR noise filter
- Radiation tolerance
- Faster ADC
- Higher rate capability
- L0 trigger capable
- Internal reference voltages
- Less sensitive to process variations

		North Control of Contr	
	TOFHIR1	TOFHIR2	
Number of channels	16	32	←───
Technology	CMOS 110 nm	CMOS 130 nm	←
Voltage supply	1.2 V, 2.5 V	1.2 V	
Reference voltages	External	Internal	
Radiation tolerance	No	Yes	←
DCR noise filter	No	Yes	
Number of analog buffers	4	8	←
TDC bin (ps)	20	20	
10-bit SAR ADC (MHz) *)	10	40	
Compatibility with lpGBT	Yes	Yes	
I/O links	LVDS	CLPS	
L1, L0 Trigger	Yes, No	Yes, Yes	
Maximum MIP rate/ch (MHz)	1	2.5	
Max low E rate/ch (MHz)	3	5	←
Clock frequency (MHz)	160	160	1

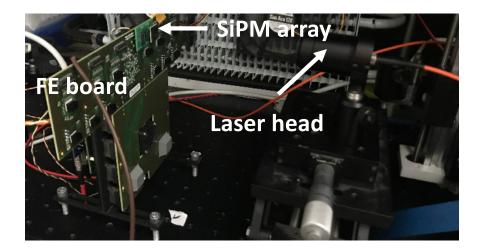
*) SAR ADC 40 MHz provided by Krakow group

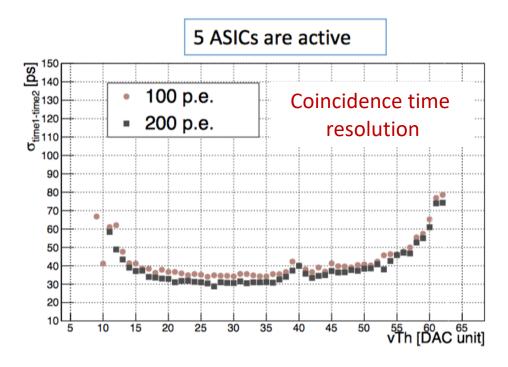
TOFHIR2 8.5 x 5.2 mm²

Measurements with TOFHIR1

- FE board with 6 TOFHIR1 chips
- Picosecond laser
- SiPM array S13361-3050AE
- Measured coincidence time resolution between channels
- Single channel time resolution with laser pulse of 200 p.e. is 21 ps.
 - Same slew rate as 8000 pe LYSO
 - Adding the contribution of photostatistics we expect a time resolution of 31 ps with LYSO

TOFHIR1 has already enabled system level testing

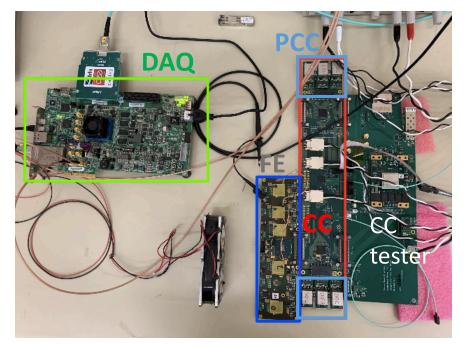




Readout Unit prototype 1

- The RUproto1 integrates Frontend board (FE), Concentrator Card (CC), and Power Converter Card (PCC)
- Integration of RUproto1 with backend DAQ is being carried-out at CERN
 - Configuration and data readout of test data via lpGBT/VTRX+ was achieved
 - Communication with GBT-SCAs and temp monitoring were achieved
 - Tests with sensors were postponed due to COVID-19





Expected time resolution TOFHIR2

Simulation conditions

	BoL	EoL
LYSO pulse	9500 p.e.	6000 p.e.
SiPM gain	3.8 10 ⁵	1.5 10 ⁵
SiPM jitter	100 ps	100 ps
SiPM cross-talk	14%	3%
TDC digitization	20 ps	20 ps

Time resolution at discriminator output

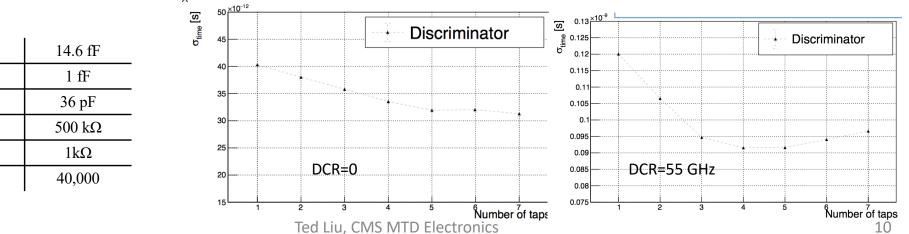
- LYSO photo-statistics included
- TDC digitization added
- Clock jitter 15 ps

LYSO double readout

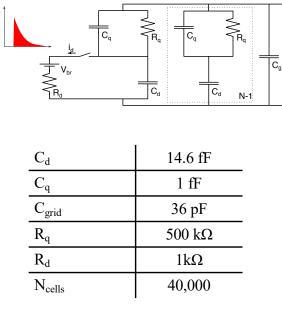
DCR (GHz)	0	30	40	60
$\sigma_{ m t}$ (ps)	25	55	60	68

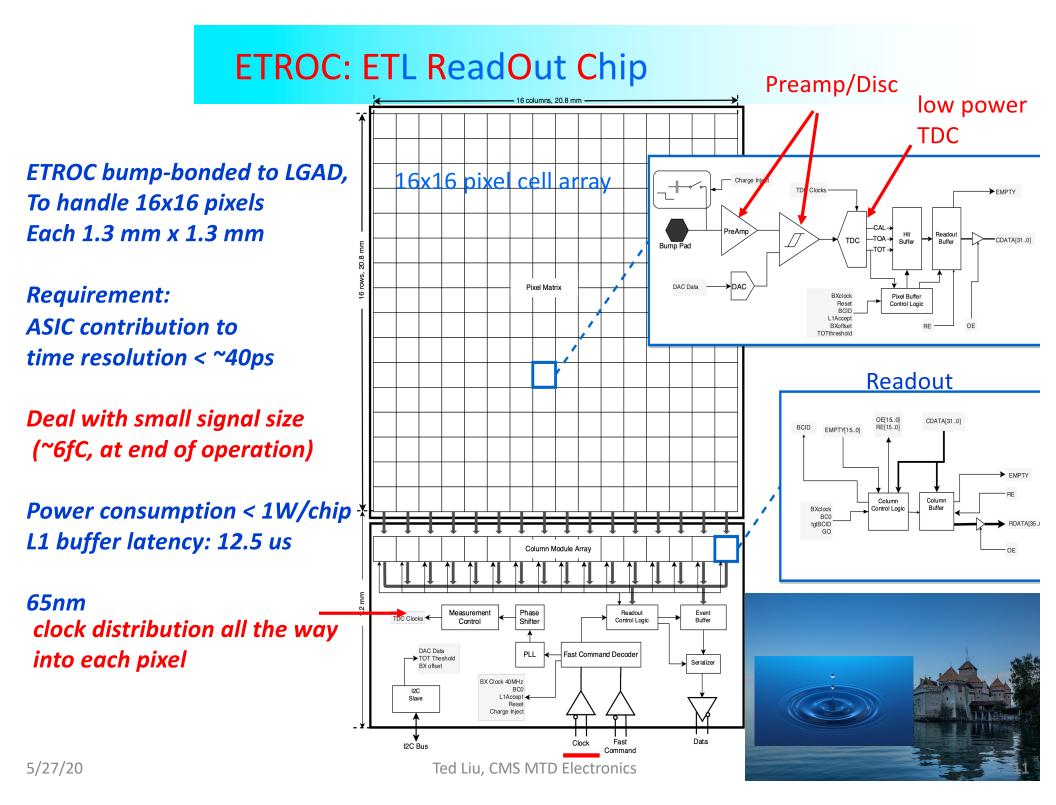
DCR at 3000 fb⁻¹ for different scenarios of operating and annealing temperatures under study.

$\sigma_{ m t}$ (ps) single-ended readout LYSO bar

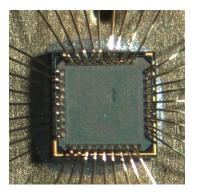


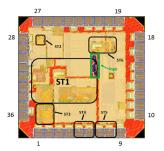
SiPM model





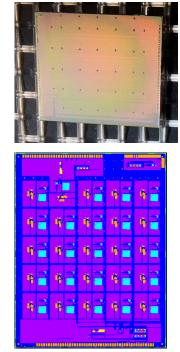
From ETROC0 to ETROC1 to ETROC2





ETROC0

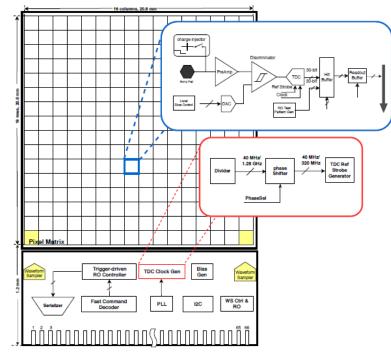
- Submitted in Dec. 2018
- Analog Front-end
- Tests by far confirmed functionality
- First round beam test early 2020



ETROC1

- Submitted in Aug. 2019
- 4 X 4 pixel array with full front-end including TDC
- Chips received middle Dec 2019
- o TDC block works well
- Single pixel full chain testing on going (slowed down by COVID 19), and followed by 4x4 array testing

Design team: FNAL/SMU in collaboration with IpGBT team



ETROC2

- Aim to submit in Q1 2021
- Designed to be compatible with 16 X 16 pixel array with *full functionalities*

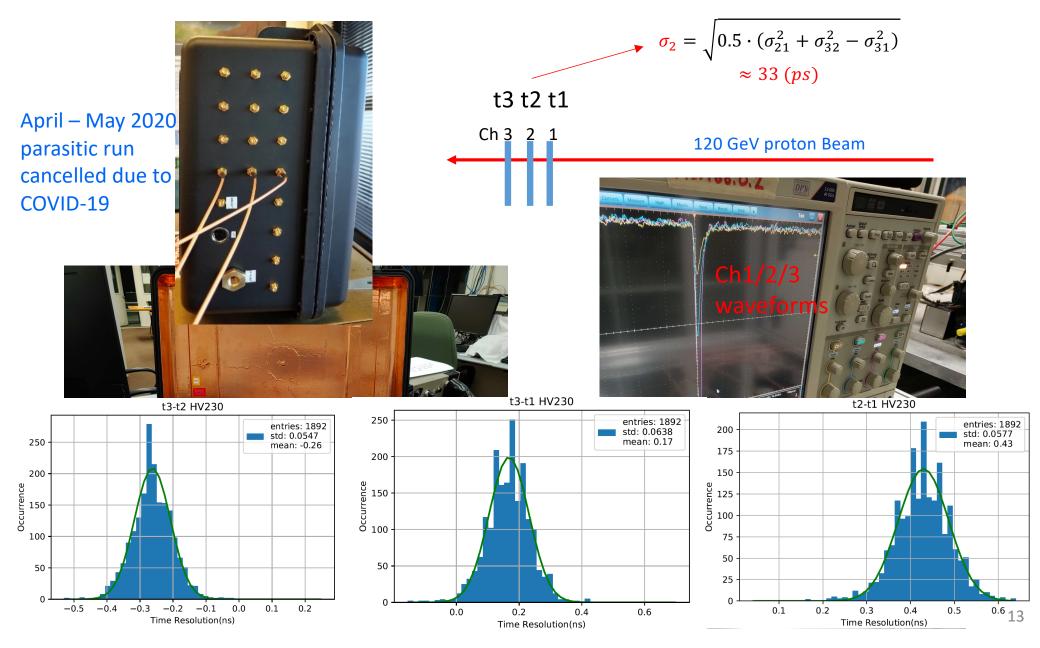
ETROC3

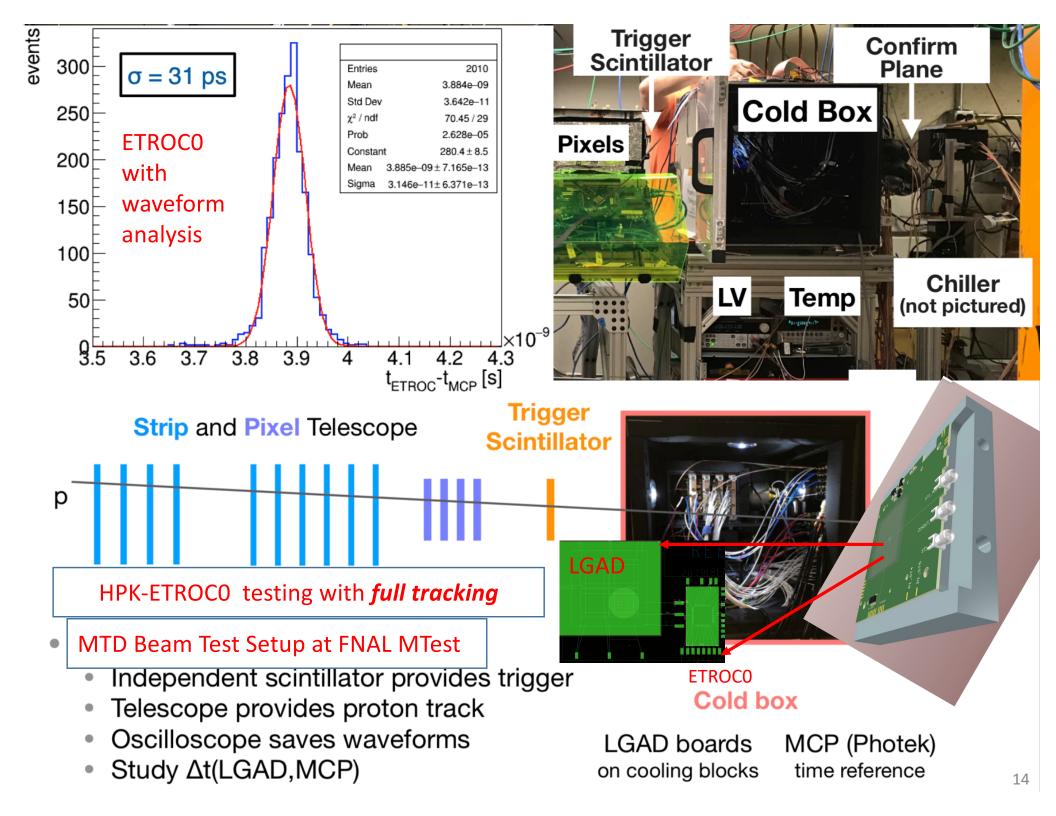
- Aim to submit in Q1 2022
- Pre-production version

A simple Beam Telescope (with 3 HPK-ETROCO boards)



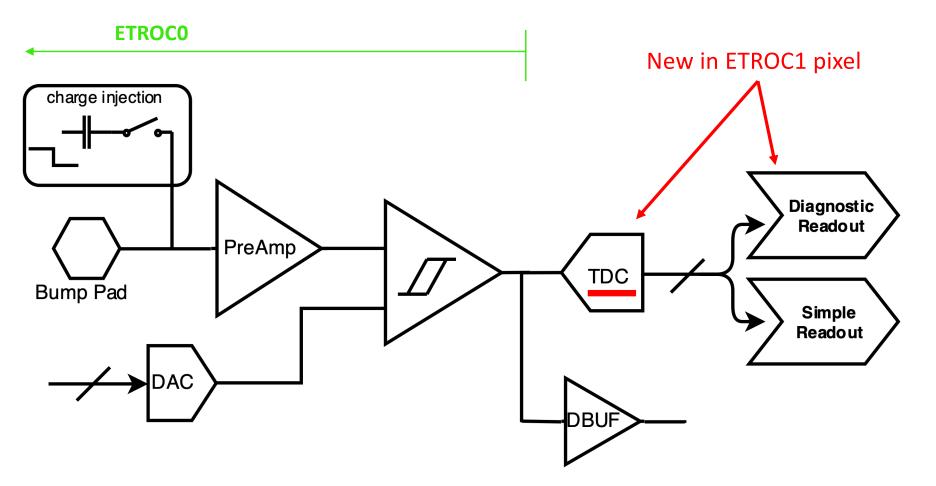
Simple "suitcase" setup in parasitic mode running at FNAL MTest





ETROC1 pixel: uses ETROC0 front-end

ETROC0 is used directly in **ETROC1**

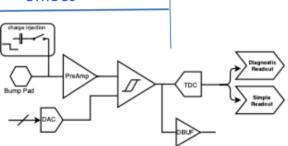


The TDC is brand new design (low power) ~ one year development effort

ETROC1 TDC Design

- TDC requirements
 - TOA bin size < ~30ps, TOT bin size < ~100ps</p>
 - Lower power highly desirable
 - ETROC TDC design goal: < 0.2mW per pixel
- ETROC TDC design optimized for low power
 - A simple delay line without the need for DLL's to control individual delay cells, with a cyclic structure to reduce the number of delay cells, to measure TOA & TOT at the same time
- In-situ delay cell self-calibration technique
 - For each hit, will use two consecutive rising clock edges to record two time stamps, with a time difference of the known 320 MHz clock period: 3.125ns
 - Crucial to reach the required precision using a tapped delay line with uncontrolled delay cells (thus lower power)

ETROC0



ETROC1 Single Pixel Layout

Extensive design verification has been done, mostly by EE students.

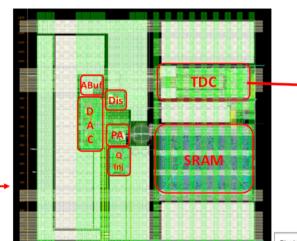
Low power TDC: <0.1mW

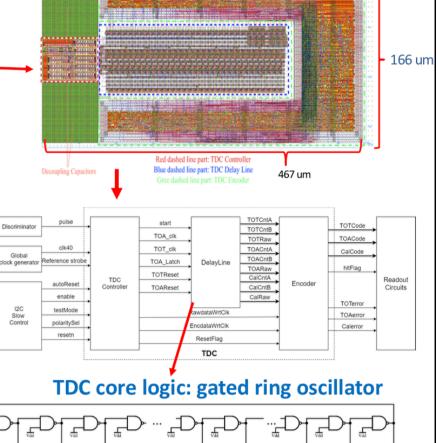


God-parent reviews in May and July 2019

ETROC1 submitted on time (Aug 28, 2019)

Chips arrived middle Dec 2019

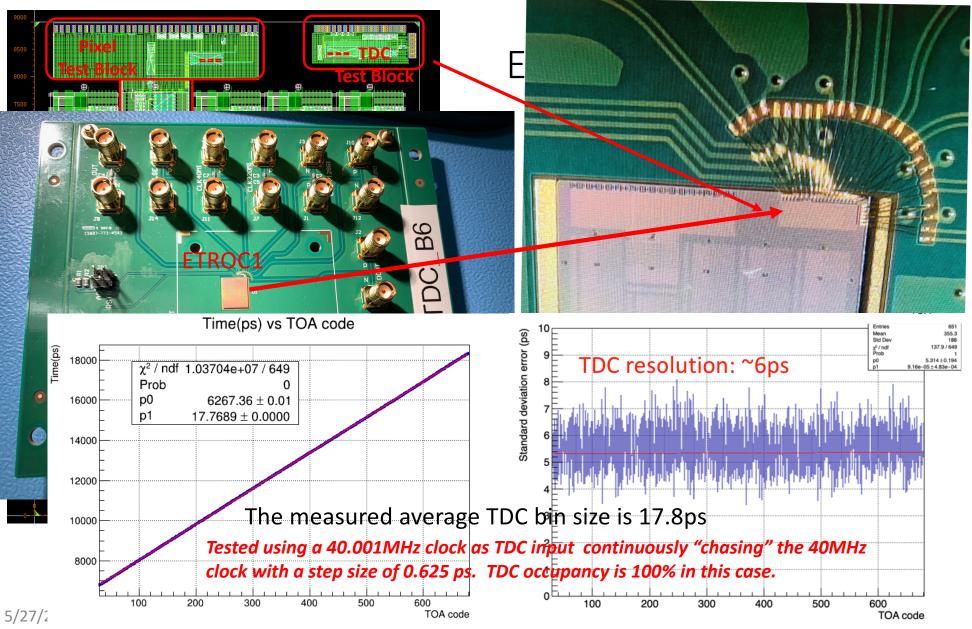




Ted Liu, CMS MTD Electronic

ETROC1 TDC resolution: ~ 6ps

ETROC1 Top Layout



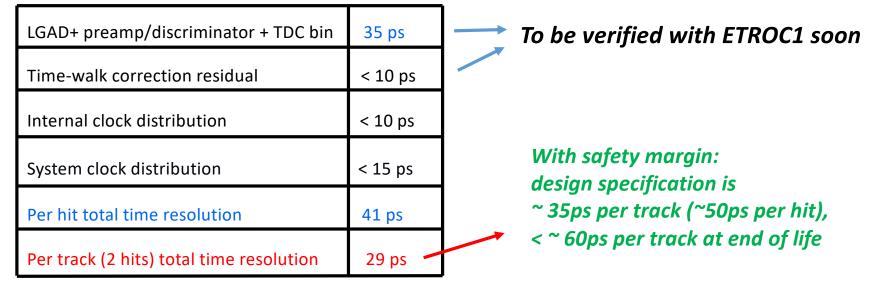
ETROC2&3: already on going

ETROC specification has been developed (TDR)

- Most critical components implemented in ETROC0&1
- PLL is based on newly improved version from lpGBT
 - Mini-ASIC submitted last week
- Full-chip clock distribution design advanced
 - The textbook H-tree clock distribution
- Waveform sampling spec and design developed
 - Single channel ADC prototype received last year, works well
 - The core 2.56 GS/s waveform sampler submission in Feb 2020
 - Mini-ASIC received two weeks ago
- Much of the supporting circuitries will be based on existing design blocks in 65nm from CERN (lpGBT)

Overall expected ETROC performance

Time resolution



Power consumption

Circuit component	Power per channel [mW]	Power per ASIC [mW]
Preamplifier (low-setting)	0.67	171.5
Preamplifier (high-setting)	1.25 - All confirmed	320
Discriminator	0.71	181.8
TDC	0.2 - achieved 0.1mW	51.2
SRAM	0.35	89.6
Supporting circuitry	0.2	51.2
Global circuitry		200
Total (low-setting)	2.13	745
Total (high-setting)	2.71	894

With safety margin: design specification is ~ 1W per chip

Summary of ETL ETROC Status

done

done (see backup)

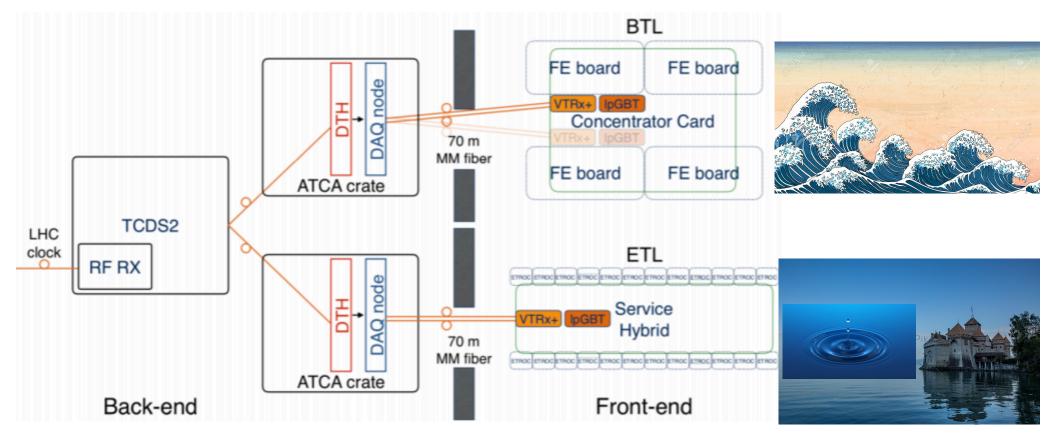
done (see backup)

- ETROCO
 - Charge injection
 - Cosmic
 - Laser testing
 - TID test to 100Mrads done (see backup)
 - Beam testing
- first round successful (early 2020)
- ETROC1 (chips received in Dec 2019)

 - Single pixel full chain test started, delayed (COVID-19)
 - Full ETROC1 testing
 - TDC initial testing results results good, power within spec

 - delayed (COVID-19)
 - ETROC1 and 5x5 LGAD bump-bonding delayed (COVID-19)
- ETROC2: design in progress
 - Aim for submission in Q1-Q2 2021

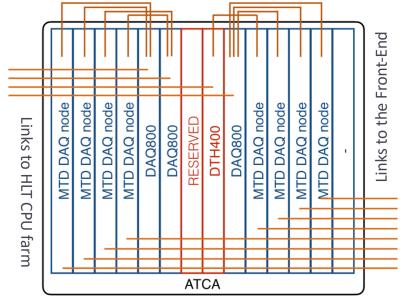
MTD electronics system



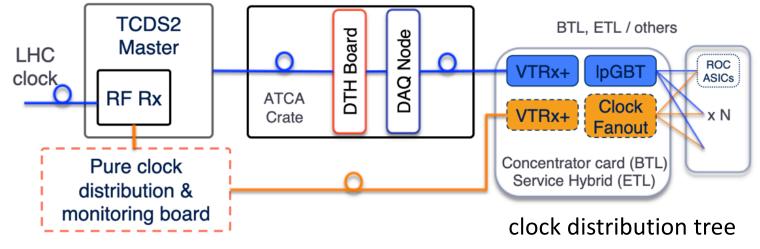
MTD DAQ and Clock distribution overview

DAQ: <0.4 Tb/s data rate at 750 kHz L1A</p>

- Number of bi-directional links and data rate
 - BTL: 864 (2x redundant); 5.5 Gb/s / link
 - ETL: 1600 links; <1.5 Gb/s / link
- Three ATCA crates with 8 (BTL) and 6+6 (ETL) MTD DAQ nodes (e.g. Serenity KUP15)
 - Being re-visited and optimized now
- Clock: <15 ps jitter (channel-to-channel)</p>
 - <u>Baseline</u>: Encoded within lpGBT links
 - <u>Risk mitigation</u>: "Pure clock path"



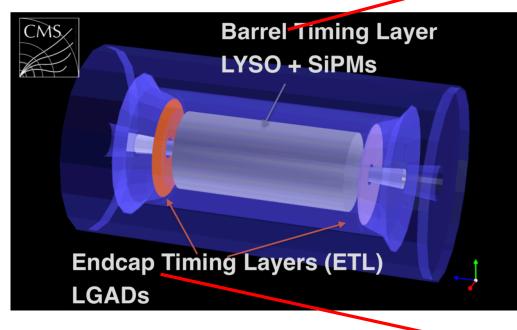
Schematic of an MTD DAQ ATCA crate layout



Summary

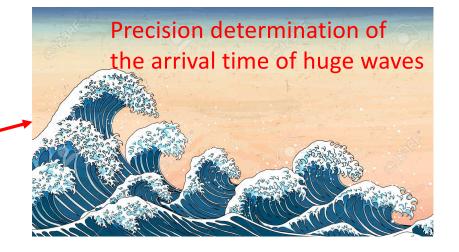
CMS MTD BTL and ETL are among the first generation precision timing detectors:

challenging front-end electronics design, tons of progress have been made over recent years Exciting time ahead of us ...





with 30-40 ps per track resolution at HL-LHC start, & <60 ps at 3000 fb⁻¹



Precision determination of the arrival time of small water drop ripples

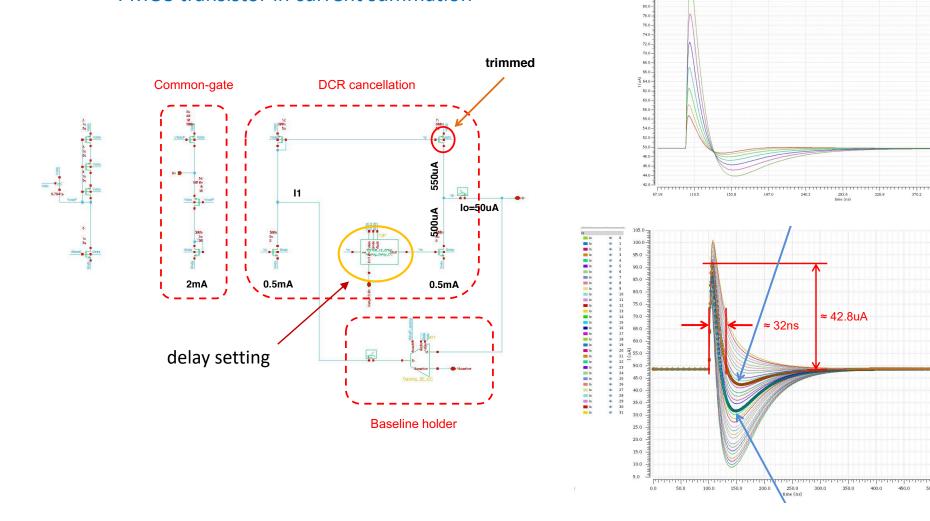
Backup slides

TOFHIR: Trimming the pulse shape

82.0

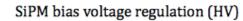
Trimming of the pulse shape to cope with PVT variations

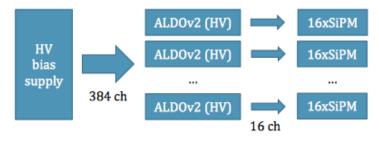
- DCR cancelation delay (200-500 ps)
- PMOS transistor in current summation



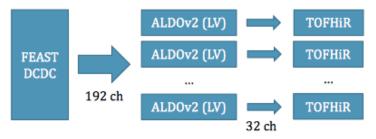
BTL ALDO2 ASIC

- SiPM bias voltage regulation
 - Finer segmentation and adjustable regulation
 - 16 channels for each independent bias line
 - Dark current measurement
- TOFHiR power supply regulation
 - Filter noise on power supply
 - Improve thermal and load stability
 - Finer segmentation
 - 1 TOFHiR for each ALDO



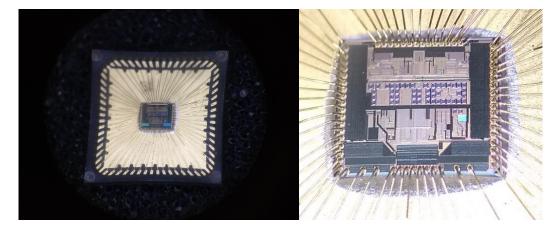


TOFHiR power supply regulation (LV)



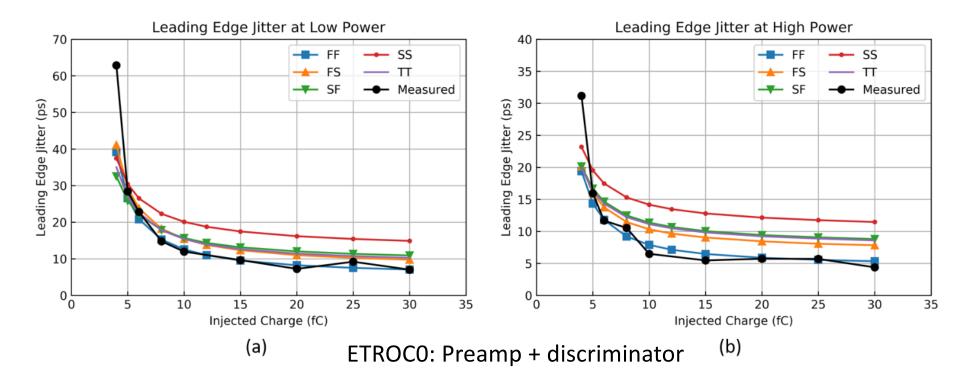
- Performance matches the simulation
- Radiation tests to be done

Details see ACES poster by Paolo Carniti.



ETROCO jitter: measured vs simulation

ETROC0 post-layout simulation vs testing results using 25ps risetime external pulse injection

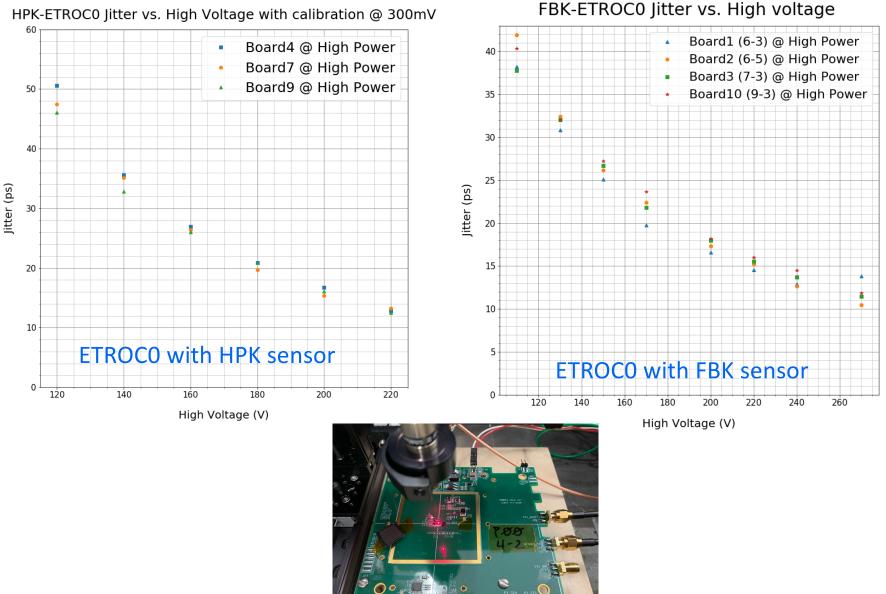


Summary of the charge injection testing: Discriminator leading edge jitter measurements agree with chip post-layout simulation

Power consumption for preamp and discriminator all match with simulation

Testing ETROCO boards with laser before beam

HPK-ETROCO and FBK-ETROCO boards prepared in Jan 2020

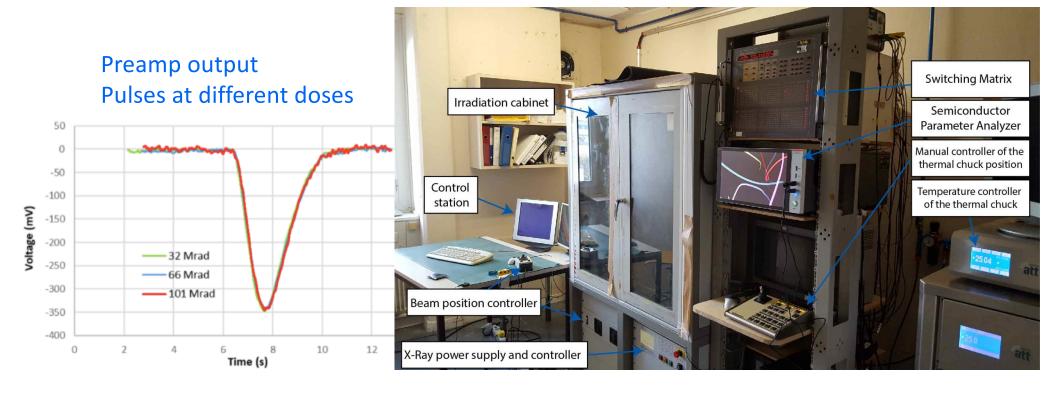


HPK-ETROC0 Jitter vs. High Voltage with calibration @ 300mV

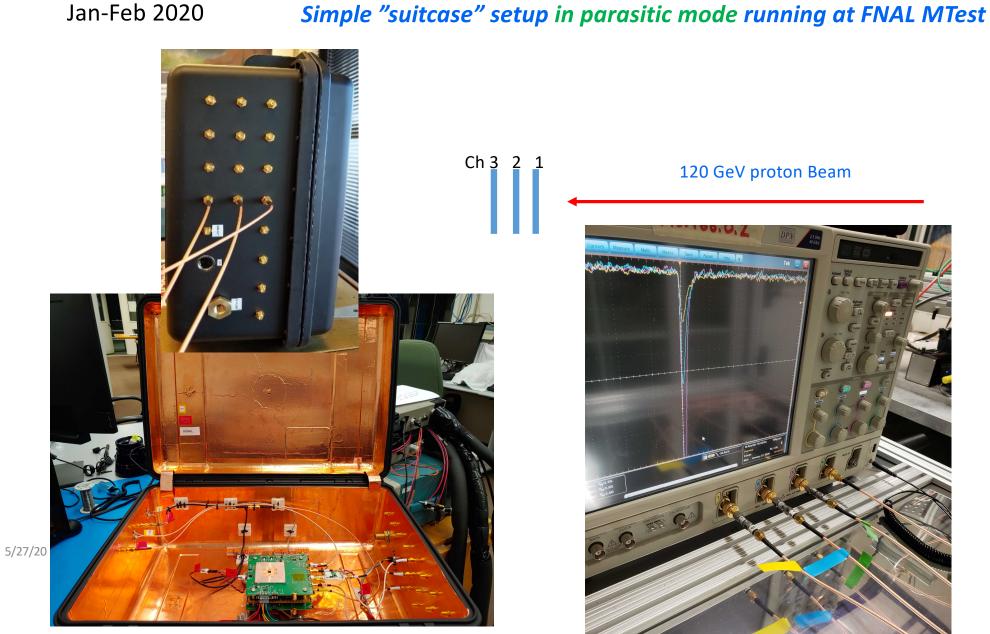
ETROCO TID testing at CERN: Dec 2019

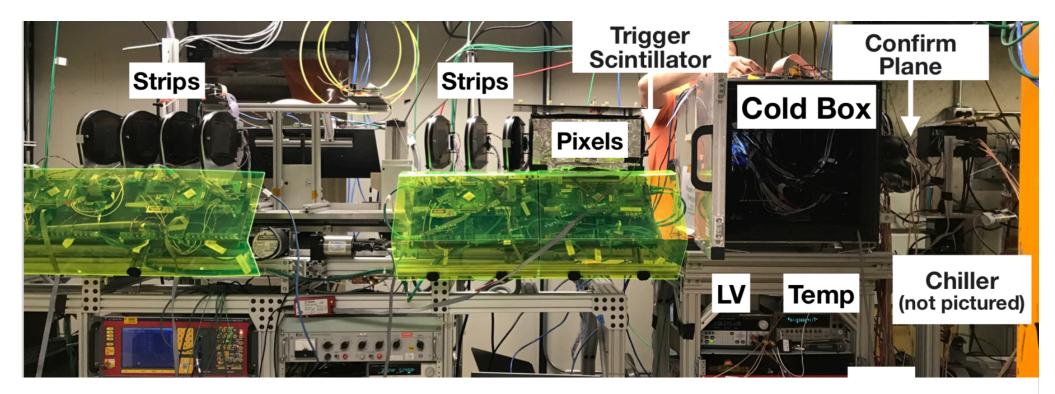
ETROCO has been tested with TID up to 100Mrad: no issue found.

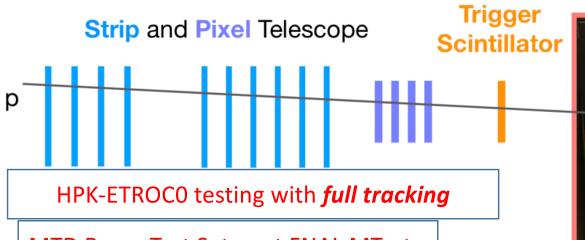
CERN x-ray irradiation facility: AsteriX, Tube voltage: 40 kV. Tube current: up to 50 mA. Calibrated dose rate up to 8.09 Mrad/hr https://espace.cern.ch/projectxrayese/_layouts/15/start.aspx#/AsteriX/Forms/AllItems.aspx



A simple ETROCO Beam Telescope (3 boards)







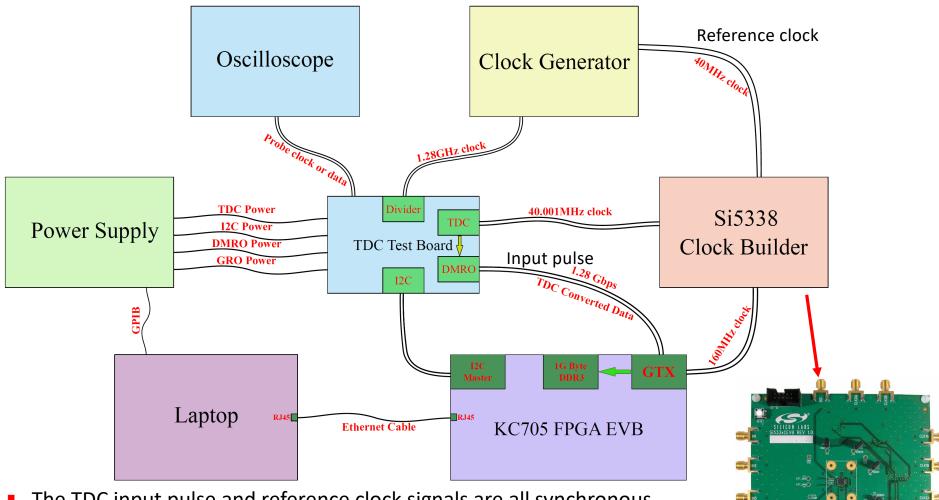
- MTD Beam Test Setup at FNAL MTest
 - Independent scintillator provides trigger
 - Telescope provides proton track
 - Oscilloscope saves waveforms
 - Study Δt(LGAD,MCP)

Cold box

LGAD boards on cooling blocks

MCP (Photek) time reference

ETROC1 TDC performance study setup



- The TDC input pulse and reference clock signals are all synchronous
- Use 40.001 MHz synchronous clock as TDC input,

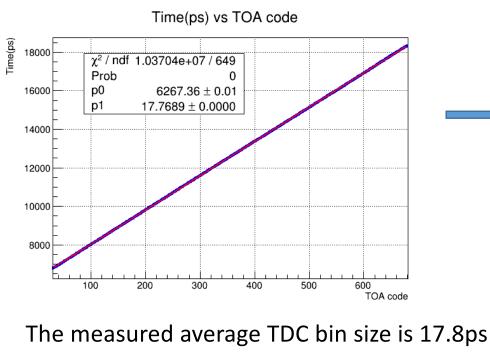
it is continuously "chasing" the 40MHz clock with a step size of 0.625 ps

• When $f_0 = 40$ MHz and $\Delta f = 1$ kHz. The phase step size is 0.625 ps

The TDC resolution estimate

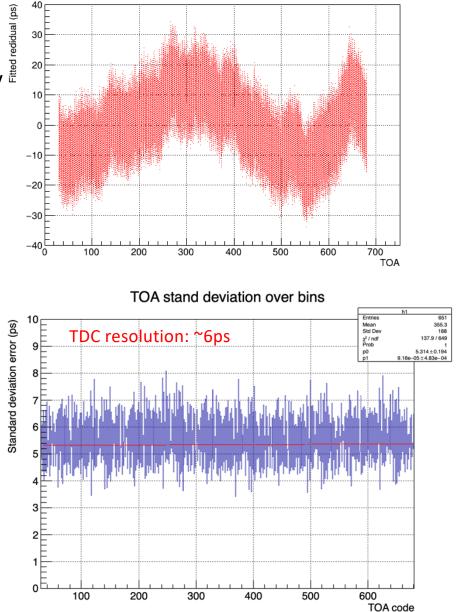
((Evt-13000)%40000)*0.625-(6267.36+17.7689*TOA):TOA (Evt>13000&&Evt<9980000&&Hil==1&&TOA>=30&&TOA<=680)

Tested with 100% TDC occupancy. for real operation: up to few % occupancy. The testing at lower occupancy was interrupted by COVID-19.

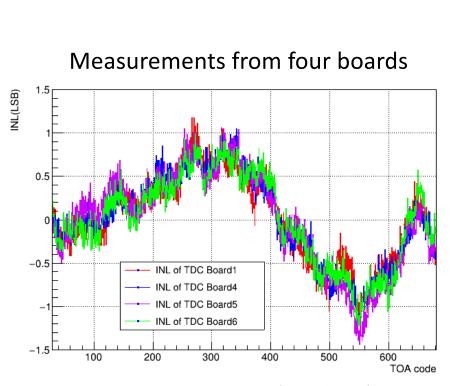


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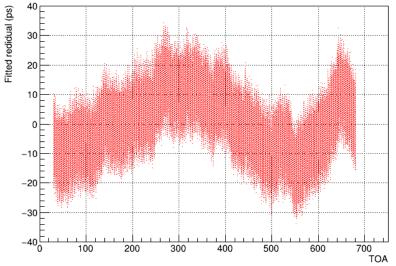
Ted Liu, CMS MTD Electronics



TDC INL measured from four boards



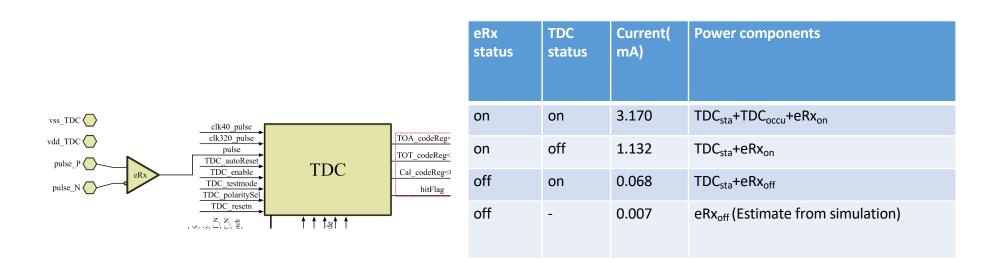
((Evt-13000)%40000)*0.625-(6267.36+17.7689*TOA);TOA (Evt>13000&&Evt<9980000&&Hit==1&&TOA>=30&&TOA<=680}





Ted Liu, CMS MTD Electronics

TDC Power consumption measurement



- The measured power of TDC block includes eRx and TDC core.
 - Both TDC and eRx can be turned on/off by I2C interface.
- We assume TDC power comprises of standby power (when no incoming hit), and occupancy power
- The measured TDC occupancy power is 2.446 mW = 1.2x(3.170-1.132);
- The current of eRx is estimated to be 7uA when it is off, the standby power of TDC is 73 uW = 1.2*(68-7) uW
- When occupancy is 100%, the TDC power is 2.519 = 2.446+0.073 mW
- When occupancy is 1%, the TDC power is 73+2446*1% = 97 uW Ted Liu, CMS MTD Electronics